

TG-NSP36K Non-Silicone Thermal Putty

Version 3.080618



Non-Silicone Thermal Putty

TG-NSP36K is a non-silicone based thermally conductive putty, suitable for use as a thermal interface material for cooling of electronic devices. This material is designed to optimize flow from a dispensing system and also provides a low thermal impedance for enhanced cooling.

Features

Excellent thermal conductivity 4.5W/mK Fully cured and reworkable Ideal for wide range of gaps Fully supported optimisation of dispense systems

Applications

Consumer electronics Power supplies and semi-conductors Automotive LED lighting

Properties

REACH Compliant
ROHS Compliant

Property	TG-NSP36K	Unit	Tolerance	Test Method
Colour	Light grey	-	-	Visual
MIx ratio, by weight	One component	-	-	-
Extrusion rate, 2.5mm orifice, 50psi, 25°C	2.0	g/min	-	-
Temperature Range	-40 to 200	°C	-	-
Flow Test, 45° incline	Non flow	mm	-	-
Specific Gravity 25°C	3.1	-	-	ASTM D792
Thermal Conductivity	4.5	W/mK	-	ASTM D5470
Volatile Content	<0.5	%	-	ASTM E595
Oil Bleeding 100°C/100h	50	mm	-	-
Shelf Life	12	months	-	-

Standard Packaging

Size	Pot	Weight (gr)	
	Syringe	30ml	
	Syringe	55ml	
	Jar	500g	
	Metal Pail	9kg	

Storage

Tightly close original container of unused product. Store in a cool and dark place.

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